NVMJS1D4N06CL

Product Preview <u>MOSFET</u> – Power, Single N-Channel 60 V, 1.4 mΩ, 220 A

Features

- Small Footprint (5x6 mm) for Compact Design
- Low R_{DS(on)} to Minimize Conduction Losses
- Low Q_G and Capacitance to Minimize Driver Losses
- LFPAK8 Package, Industry Standard
- AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free and are RoHS Compliant

	(1) = 20 (nee netea)		
Parameter			Symbol	Value	Unit
Drain-to-Source Voltage			V _{DSS}	60	V
Gate-to-Source Voltage	Э		V _{GS}	±20	V
Continuous Drain	Steady	$T_{C} = 25^{\circ}C$	۱ _D	220	А
Current R _{θJC} (Notes 1, 3)	State	T _C = 100°C		156	
Power Dissipation		T _C = 25°C	PD	136	W
$R_{\theta JC}$ (Note 1)		$T_{C} = 100^{\circ}C$		68	
Continuous Drain	Steady	T _A = 25°C	۱ _D	37	А
Current R _{θJA} (Notes 1, 2, 3)	State	$T_A = 100^{\circ}C$		26	
Power Dissipation		T _A = 25°C	PD	3.8	W
$R_{\theta JA}$ (Notes 1 & 2)		T _A = 100°C		1.9	
Pulsed Drain Current	$T_A = 25^{\circ}C, t_p = 10 \ \mu s$		I _{DM}	900	А
Operating Junction and Storage Temperature			T _J , T _{stg}	–55 to + 175	°C
Source Current (Body Diode)			ا _S	TBD	А
Single Pulse Drain-to-Source Avalanche Energy (I _{L(pk)} = 15 A)			E _{AS}	TBD	mJ
Lead Temperature for Soldering Purposes (1/8" from case for 10 s)			ΤL	260	°C

MAXIMUM RATINGS (T₁ = 25°C unless otherwise noted)

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL RESISTANCE MAXIMUM RATINGS

Parameter	Symbol	Value	Unit
Junction-to-Case - Steady State	$R_{\theta JC}$	1.1	°C/W
Junction-to-Ambient - Steady State (Note 2)	R_{\thetaJA}	39	

1. The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted.

- Surface-mounted on FR4 board using a 650 mm², 2 oz. Cu pad.
- 3. Maximum current for pulses as long as 1 second is higher but is dependent on pulse duration and duty cycle.

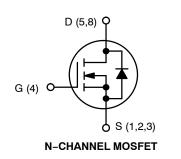
This document contains information on a product under development. ON Semiconductor reserves the right to change or discontinue this product without notice.

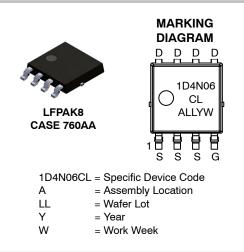


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V _{(BR)DSS}	R _{DS(ON)} MAX	I _D MAX
60 V	1.4 mΩ @ 10 V	220 A
60 V	$2.37~\mathrm{m}\Omega$ @ $4.5~\mathrm{V}$	220 A





ORDERING INFORMATION

See detailed ordering, marking and shipping information on page 3 of this data sheet.

NVMJS1D4N06CL

ELECTRICAL CHARACTERISTICS (T_J = $25^{\circ}C$ unless otherwise specified)

Parameter	Symbol	Test Condition		Min	Тур	Max	Unit
OFF CHARACTERISTICS						-	-
Drain-to-Source Breakdown Voltage	V _{(BR)DSS}	V_{GS} = 0 V, I_D = 250 μ A		60			V
Drain-to-Source Breakdown Voltage Temperature Coefficient	V _{(BR)DSS} / T _J				12.7		mV/°C
Zero Gate Voltage Drain Current	I _{DSS}	$V_{GS} = 0 V,$	T _J = 25 °C			10	μA
		V _{DS} = 60 V	T _J = 125°C			250	
Gate-to-Source Leakage Current	I _{GSS}	V _{DS} = 0 V, V _{GS}	= ±16 V			±100	nA
ON CHARACTERISTICS (Note 4)							
Gate Threshold Voltage	V _{GS(TH)}	$V_{GS} = V_{DS}, I_D$	= 250 μA	1.2		2.0	V
Threshold Temperature Coefficient	V _{GS(TH)} /T _J				TBD		mV/°C
Drain-to-Source On Resistance	R _{DS(on)}	V _{GS} = 4.5 V	I _D = 50 A		1.9	2.37	mΩ
		V _{GS} = 10 V	l _D = 50 A		1.12	1.4	
Forward Transconductance	9 _{FS}	V _{DS} =15 V, I _D	= 50 A		TBD		S
CHARGES, CAPACITANCES & GATE RE	SISTANCE	•					
Input Capacitance	C _{ISS}	V_{GS} = 0 V, f = 1 MHz, V_{DS} = 25 V			7283		pF
Output Capacitance	C _{OSS}				3025		1
Reverse Transfer Capacitance	C _{RSS}				31		
Total Gate Charge	Q _{G(TOT)}	V_{GS} = 4.5 V, V_{DS} = 30 V; I_{D} = 50 A			45		nC
Total Gate Charge	Q _{G(TOT)}	V_{GS} = 10 V, V_{DS} = 30 V; I_{D} = 50 A			101		
Threshold Gate Charge	Q _{G(TH)}	V _{GS} = 4.5 V, V _{DS} = 30 V; I _D = 50 A			TBD		
Gate-to-Source Charge	Q _{GS}				20		-
Gate-to-Drain Charge	Q _{GD}				10		
Plateau Voltage	V _{GP}				TBD		V
SWITCHING CHARACTERISTICS (Note 5	ō)					-	-
Turn–On Delay Time	t _{d(ON)}	V _{GS} = 4.5 V, V _D I _D = 50 A, R _G	_S = 30 V,		TBD		ns
Rise Time	tr	I _D = 50 A, R _G	$_{i} = 1 \Omega$		TBD		
Turn-Off Delay Time	t _{d(OFF)}				TBD		
Fall Time	t _f				TBD		
DRAIN-SOURCE DIODE CHARACTERIS	STICS						
Forward Diode Voltage	V _{SD}	V _{GS} = 0 V,	$T_J = 25^{\circ}C$		0.78	1.2	.2 V
		I _S = 50 A	T _J = 125°C		0.66		
Reverse Recovery Time	t _{RR}	V _{GS} = 0 V, dI _s /dt = 100 A/µs, I _S = 50 A			TBD		ns
Charge Time	t _a				TBD		
Discharge Time	t _b				TBD		
Reverse Recovery Charge	Q _{RR}				TBD		nC

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions. 4. Pulse Test: pulse width \leq 300 µs, duty cycle \leq 2%. 5. Switching characteristics are independent of operating junction temperatures.

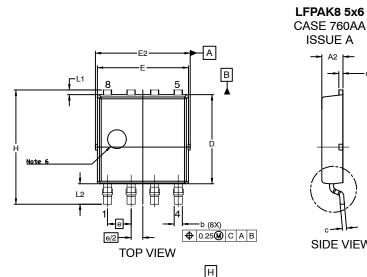
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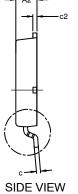
DEVICE ORDERING INFORMATION

Device	Marking	Package	Shipping [†]
NVMJS1D4N06CLTWG	1D4N06CL	LFPAK8 (Pb–Free)	1500 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

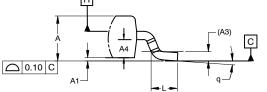
PACKAGE DIMENSIONS



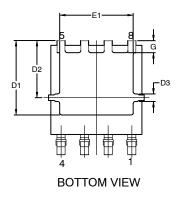


NOTES:

- DIMENSIONING AND TOLERANCING 1.
- PER ASME Y14.5M, 1994. 2. CONTROLLING DIMENSION:
- MILLIMETERS. DIMENSIONS D AND E DO NOT 3.
- INCLUDE MOLD FLASH, PROTRUSIONS, OR BURRS. MOLD FLASH PROTRUSIONS OR GATE BURRS SHALL NOT EXCEED 0.150mm PER SIDE.
- DIMENSIONS D AND E ARE 4 DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY.
- 5. DATUMS A AND B ARE DETERMINED AT DATUM PLANE H.
- 6. OPTIONAL MOLD FEATURE.







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1.150 1.150 1.150 1 0.700 (8X)	፼ ፼		4	I
RECON	IMEN	DED	мои	INTING

FOOTPRINT

	MILLIMETERS				
DIM	MIN	NOM	MAX		
Α	1.10	1.20	1.30		
A1	0.00	0.08	0.15		
A2	1.10	1.15	1.20		
A3	().25 REF	-		
A4	0.45	0.50	0.55		
b	0.40	0.45	0.50		
С	0.19	0.22	0.25		
c2	0.19	0.22	0.25		
D	4.70	4.80	4.90		
D1	-	-	4.20		
D2	3.00	3.10	3.20		
D3	0.30	0.40	0.50		
Е	4.80	4.90	5.00		
E1	3.90	4.00	4.10		
E2	5.00	5.15	5.30		
е	1.27 BSC				
G	0.55	0.65	0.75		
Н	6.00	6.15	6.30		
L	0.40	0.65	0.85		
L1	0.15	0.25	0.35		
L2	0.80	1.05	1.30		
q	0 °	4°	8 °		

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